

SID

Factory: Rot am See

Article:

ML4

Provided:

Customer:

Date:

18.03.2026

**WÜRTH
ELEKTRONIK**
MORE THAN
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-018my 330x490mm	50200238	18	VS	1	A00 B00
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	115		2	
B-RS-FR4-ML-0.107mm-018+018-TG150-HF-...	50203004	18	L2	3	
		107			
		18	L3		
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	115		4	
A-RS Kupferfolie-018my 330x490mm	50200238	18	RS	5	

Thickness after Pressing

B00:

390 µm

Tol+:

50 µm

Tol-:

50 µm

Dmax:

440 µm

Dmin:

340 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

500 µm

Tol+:

50 µm

Tol-:

50 µm

Dmax:

550 µm

Dmin:

450 µm

Measuring point:

(05) over SM and galv. Cu; both sides

nominal:

409 µm

Version 1.2.20.35

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